



Intellectual Property Network

[Home](#) | [Search](#) | [Order](#) | [Shopping Cart](#) | [Login](#) | [Site Map](#) | [Help](#)



JP59047751A2: COPPER ALLOY FOR LEAD WIRE MATERIAL OF SEMICONDUCTOR DEVICE

[View Images \(1 pages\)](#) | [View INPADOC only](#)

Country: **JP Japan**

Kind:

Inventor(s): **KAWAUCHI SUSUMU
TSUJI MASAHIRO
YAMAMOTO MICHIHARU**

Applicant(s): **NIPPON MINING CO LTD**
[News, Profiles, Stocks and More about this company](#)

Issued/Filed Dates: **March 17, 1984 / Sept. 13, 1982**

Application Number: **JP1982000158212**

IPC Class: **H01L 23/48; C22C 9/00;**

Abstract: **Purpose:** To obtain a lead wire material having suitable characteristics, particularly excellent adhesion of plating by defining respective components of copper- nickel-zinc alloy and limiting amounts of diversified kinds of sub-components to be mixed.
Constitution: An alloy consisting of nickel of 1.5W10wt%, zinc of 5W20wt%, oxygen of 0.0020wt% or less and remainder consisting of copper and inevitable impurities is used, or an alloy consisting of one or more metals in total weight of 0.001W2.0wt% selected from phosphorus of 0.001W0.1wt%, tin of 0.01W1.0wt%, iron of 0.005W1.0wt%, cobalt of 0.01W1.0wt%, chromium of 0.01W1.0wt%, aluminum of 0.01W1.0wt%, magnesium of 0.01W1.0wt%, manganese of 0.01W1.0wt%, titanium of 0.01W1.0wt%, zirconium of 0.01W1.0wt% and beryllium of 0.01W 1.0wt% and remainder consisting of copper and inevitable impurities are used.
COPYRIGHT: (C)1984,JPO&Japio

Other Abstract Info: none

Foreign References: (No patents reference this one)



[Nominate this
invention
for the Gallery...](#)

Alternative
Searches

[Patent Number](#)

[Boolean Text](#)

[Advanced Text](#)

Browse

[U.S. Class
by title](#)

[U.S. Class
by number](#)

TDB
[IBM Technical
Disclosure Bulletin](#)